Efficient, Fast Chip Design

As a leader in custom, analog, RF, and mixed-signal design enablement, we provide a complete solution starting with tools and methodologies that enable fast and accurate entry of design concepts all the way through verifying the designs before they are produced in silicon. By selectively automating aspects of custom IC design, we allow engineers to focus on precision-crafting their designs and the effects on circuit performance.

For designing the digital parts of chips, over the past few years we have introduced an entirely new, next-generation set of tools that improve productivity and speed the design process. This comprehensive tool family speeds the full design cycle from front-end design all the way to final silicon signoff convergence.

The Cadence® IP portfolio includes pre-designed and configurable blocks that can be integrated quickly into chip designs, freeing the design team from re-designing these elements. This portfolio includes Tensilica® DSPs for AI, vision, audio, IoT, and baseband applications; Denali® memory and storage IP; and controllers for the latest standard interfaces including PCI Express®, USB, and Ethernet. We also offer verification IP to verify interface and memory standards.

Corporate Facts

<table>
<thead>
<tr>
<th>Founded</th>
<th>1988</th>
</tr>
</thead>
</table>
| Corporate Headquarters | 2655 Seely Ave.  
San Jose, CA 95134  
USA |
| Worldwide Locations | www.cadence.com |
| NASDAQ Symbol | CDNS |
| Primary Business | Electronic design automation software, hardware, IP, and services |
To quickly verify chip designs before they are committed to silicon, the Cadence Verification Suite provides four platforms to speed the verification of every step of the design cycle. This unique mixture of software-based solutions with hardware accelerators delivers the shortest turnaround time and predictable quality. Our technology offers the only proven path for system-level power and signal integrity.

**IC Packaging Design**

The complexity and performance requirements of today’s semiconductor packages continue to increase while design resources remain static for most organizations—placing a premium on efficiency and productivity. Our IC packaging and cross-domain co-design automation provide efficient solutions in system-level co-design and advanced mixed-signal packaging, delivering the automation and accuracy to expedite the design process.

**PCB Design**

We offer leading PCB layout and routing technologies used by a wide range of designers, from casual hobby designers to companies developing extremely demanding innovative new products. Our PCB design solutions enable shorter, more predictable design cycles with greater integration of component design and system-level simulation for a constraint-driven flow for right-first time design. The right system design software and the right system simulation and analysis software can make it easy to ensure design connectivity and eliminate unnecessary system re-spins to correct connectivity mismatches in your multi-board PCB system designs.

**System Verification**

The Cadence Verification Suite supports the company's Intelligent System Design strategy, which enables system and semiconductor companies to create complete, differentiated end products more efficiently. The Verification Suite is comprised of best-in-class core engines, verification fabric technologies, and solutions that increase design quality and throughput, fulfilling verification requirements for a wide variety of applications and vertical segments.

**Services**

Cadence Services collaborates with our customers on methodology and technology adoption, silicon enablement, and talent development to enhance productivity and reduce risk.

**A Great Place to Work**

We pride ourselves on creating and sustaining a company culture, “One Cadence—One Team”, that drives market- and industry-leading innovation and business success. Cadence is recognized as a Great Place to Work around the world, including as one of Fortune Magazine’s “100 Best Companies to Work For” over the last five years. We’ve earned additional recognition as a Best Workplace for Asian Americans, Giving Back, Baby Boomers, Recent College Graduates, and Parents. The Great Place to Work lists are based on employee ratings of different aspects of their workplace culture, including the level of trust they feel toward company leaders, the pride they take in their jobs, and the camaraderie they experience with co-workers.

**For More Information**

Investor Relations: +1.408.944.7100  
Media Relations: +1.408.914.6884

**Financial Highlights**

<table>
<thead>
<tr>
<th>Year</th>
<th>Revenue ($ in billions)</th>
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<td>2010</td>
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<tr>
<td>2011</td>
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<tr>
<td>2017</td>
<td>2.0</td>
</tr>
<tr>
<td>2018</td>
<td>2.2</td>
</tr>
</tbody>
</table>

**Executive Management**

- **Lip-Bu Tan**  
  Chief Executive Officer
- **Anirudh Devgan, PhD**  
  President
- **Tom Beckley**  
  Senior Vice President and General Manager, Custom IC & PCB Group
- **Jim Cowie**  
  Senior Vice President, General Counsel and Secretary
- **Tina Jones**  
  Senior Vice President, Global Human Resources
- **Neil Kole**  
  Senior Vice President and Chief Information Officer
- **Babu Mandava**  
  Senior Vice President and General Manager, IP Group
- **Nimish Modi**  
  Senior Vice President, Marketing & Business Development
- **Chin-Chi Teng, PhD**  
  Senior Vice President and General Manager, Digital & Signoff Group
- **John Wall**  
  Senior Vice President and Chief Financial Officer
- **Neil Zaman**  
  Senior Vice President, Worldwide Field Operations